



**TARGET THICKNESS: 0.021"**  
**NUMBER OF LAYERS: 04**

## MULTILAYER PCB CONSTRUCTION SHEET

If there are max thickness requirements beyond +/- .10% overall - non-standard construction should be ordered and notes added.

<b>4 Layer StackUp (0.021") L04-021-1ozHoz</b>		<b>Thickness (inches)</b>
<b>Layer 1</b>	<b>.5 oz foil plated to approximate* thickness 0.0017"</b>	<b>0.0017</b>
Prepreg	Bonding ply (2x 1080) Average Dielectric Constant 4.5	0.0044
<b>Layer 2</b>	<b>1 oz foil thickness</b>	<b>0.0014</b>
Core	Laminate Core Average Dielectric Constant 4.5	0.008
<b>Layer 3</b>	<b>1 oz foil thickness</b>	<b>0.0014</b>
Prepreg	Bonding ply (2x 1080) Average Dielectric Constant 4.5	0.0044
<b>Layer 4</b>	<b>.5 oz foil plated to approximate* thickness 0.0017"</b>	<b>0.0017</b>
"Thickness does not include soldermask or surface finish"		<b>0.023</b>

### NOTES: